



<b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PowerPAK® 8 x 8 (HVM)</b>					
<b>STRESS</b>	<b>SAMPLE SIZE</b>	<b>DEVICE H/CYCLE</b>	<b>CONDITION</b>	<b>TOTAL FAILS</b>	<b>FAIL PERCENTAGE</b>
HAST	455	66 000	130 °C, 85 % RH	0	0.00
Pressure pot	1205	173 280	121 °C, 15 PSIG	0	0.00
Temperature cycle	2405	1 532 500	-55 °C to +150 °C	0	0.00
Solder dunk	300	47 670	260 °C, 10 s	0	0.00